

Percival for soft X-ray imaging and Post-processing

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DESY – Photon Science Detectors
MT Meeting Berlin, 12-14 June 2018

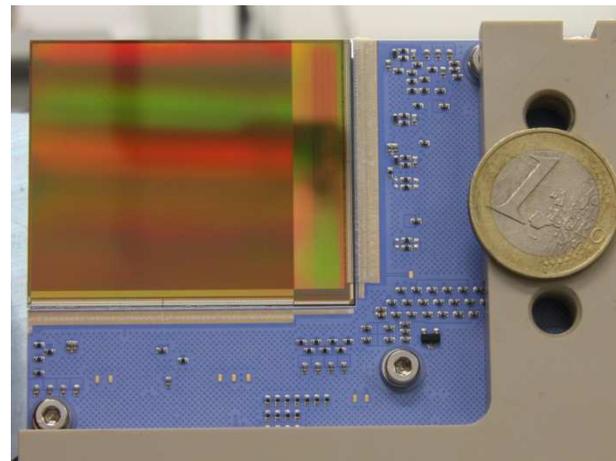
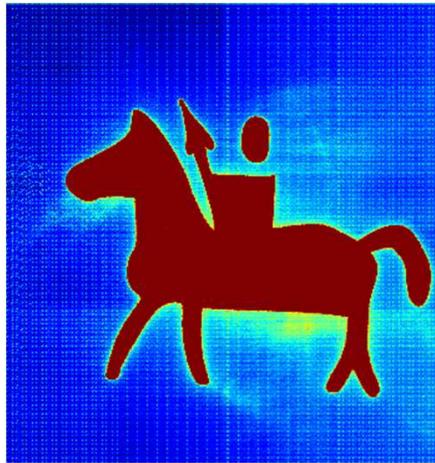
HELMHOLTZ RESEARCH FOR
GRAND CHALLENGES



Percival



Pixellated Energy-Resolving CMOS Imager, Versatile And Large



Unprecedented combination:

1408 × 1484 pixels

300 Hz frame rate

below 15 e⁻ noise

sensitive to single photons

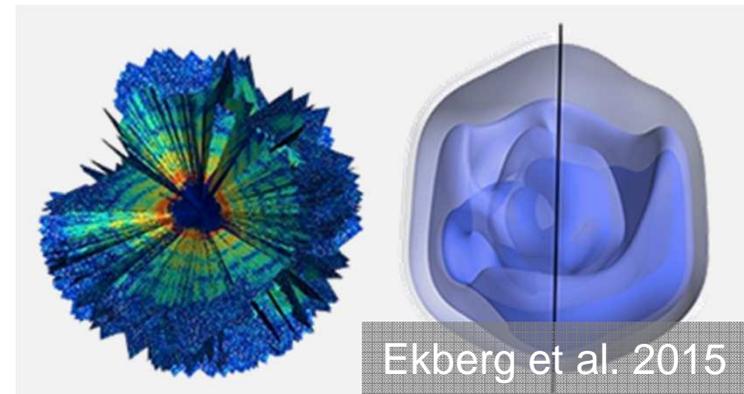
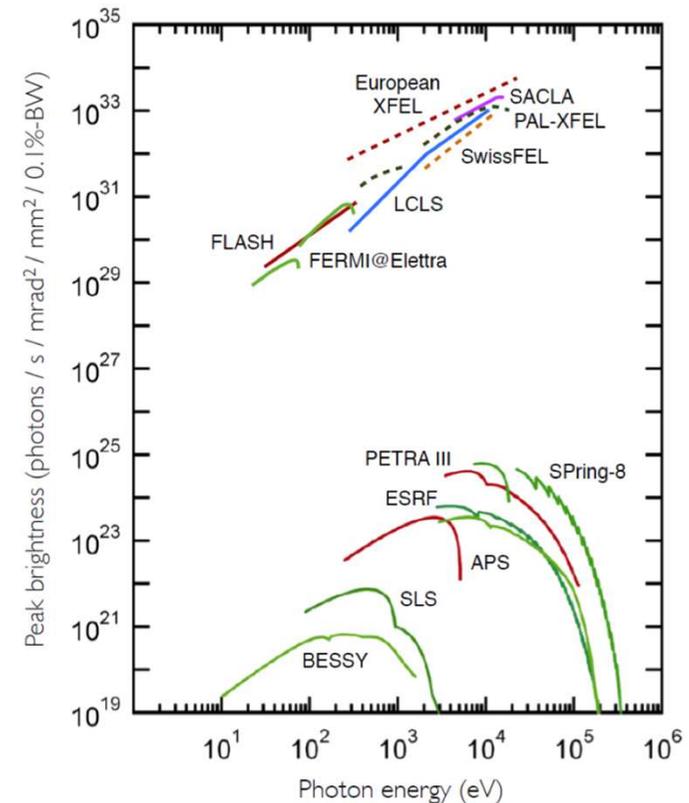
handle 5 · 10⁴ ph/pix/frame



Science Motivation

Watching biomolecules in action ... and more

- Making optimal use of the brilliance of today's photon sources requires
 - Single-shot imagers with suitable frame rates
 - Very large dynamic range
 - single-photon discrimination to
 - 10^4 photons/pixel/frame and more
 - Millions of pixels with little/no dead area
- In the soft X-ray regime
 - Scientific interest e.g. biosystems, weakly scattering samples
 - Particular challenge: small signal requires very low noise
 - Particular challenge: sensor surface

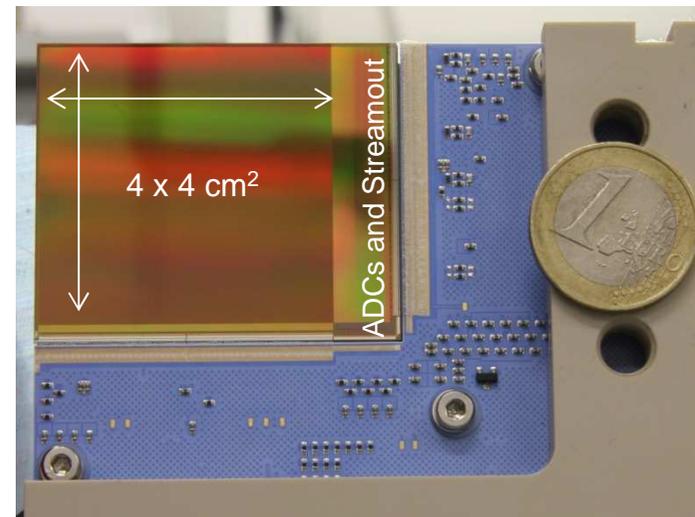


Percival P2M Sensor



Designed by partner Rutherford Appleton Lab / STFC

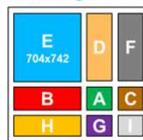
- CMOS imager (180nm technology)
- On-chip digitization (11520 ADCs)
- 3 auto-adjusting gain levels (per pixel, per frame, overflow)
- 1408 × 1484 pixels, 27μm × 27μm
- ~ 4 × 4cm² continuous imaging area (stitched sensor)



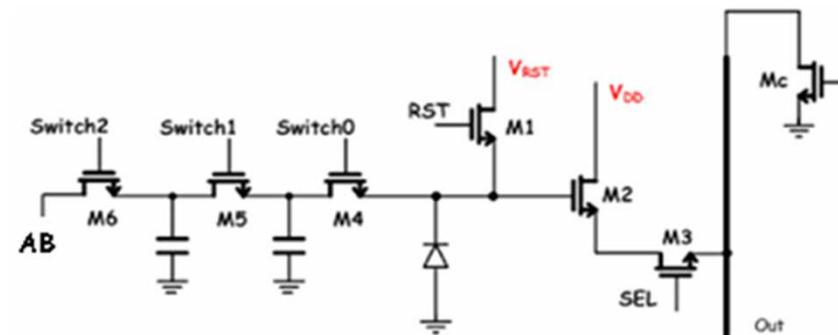
1408 x 1484 pixel variant, ~4x4cm² "intermediate step"



stitching blocks



3520 x 3710 pixel variant, ~ 10x10cm²



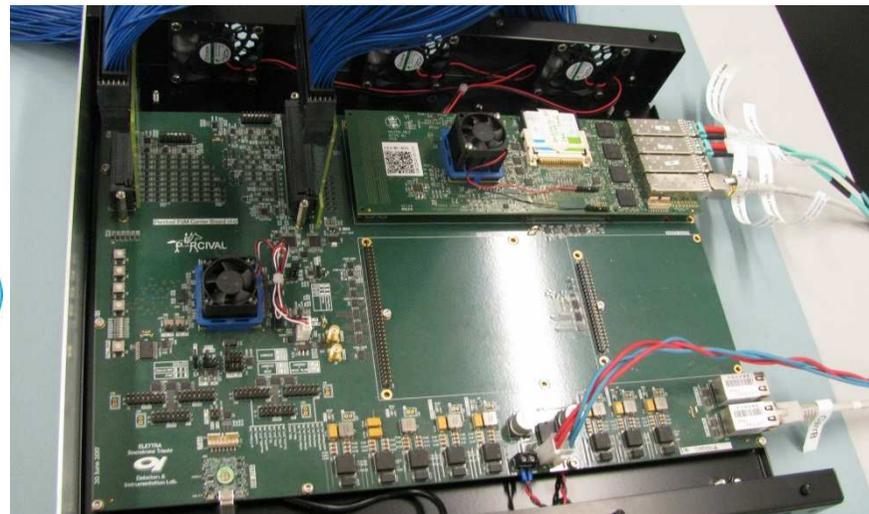
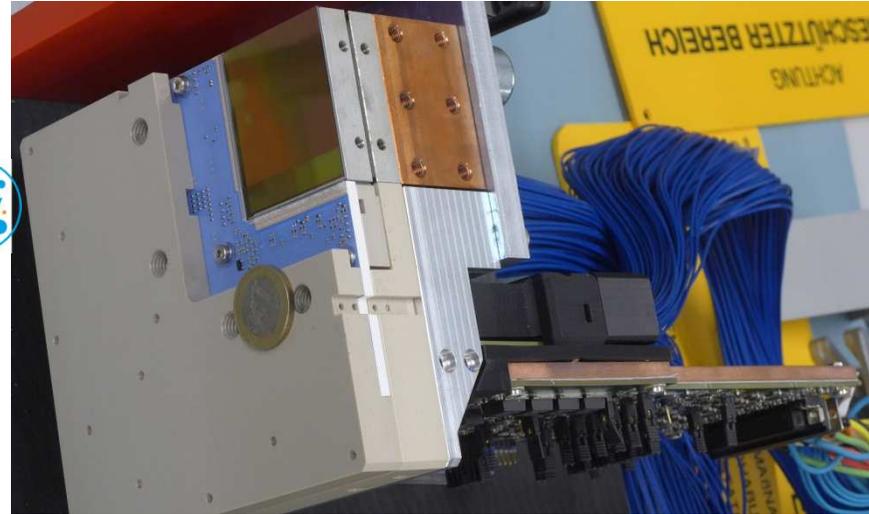
Multi-Gain Pixel Design

Percival P2M System



Currently undergoing benchtop tests in front-illuminated configuration

- In-vacuum detector head 
 - sensor 
 - Includes sensor biasing board 
 - Several hundred LVDS control & data lines, are (re)distributed here 
 - Sensor will be cooled to $\sim -30^{\circ}\text{C}$
 - 2-side buttable 
 - movable
- Carrier board hosts 
 - FPGA running finite state machine 
 - Mezzanine board (also AGIPD, Lambda) streaming out 20 Gbit/s data 
 - Interface to slow control, facility information, trigger

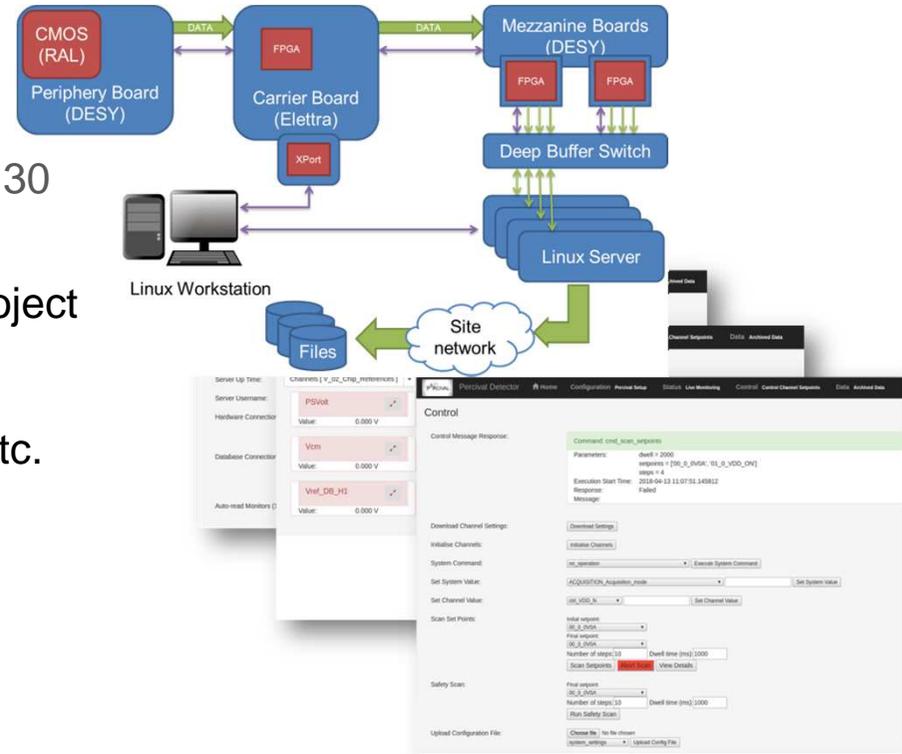


Percival P2M System



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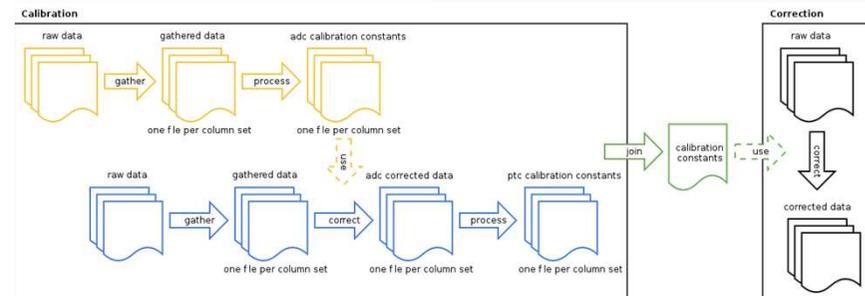
- Control & DAQ 
 - 20 Gbit/s from one sensor (reading full images: 300 Hz, 2M pixels, 30 bit/pixel incl. CDS)
 - Virtual hdf5 developed in part for this project
 - Python interface & Odin GUI interface
 - API for link to Tango, DOOCs, EPICS, etc.



- Software Framework for Characterization  

- Data validation
- Calibration constants
- Sensor characterization

- Testing   

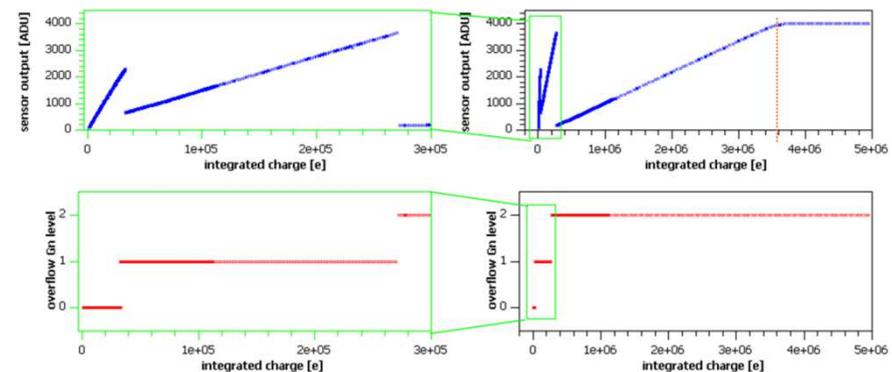
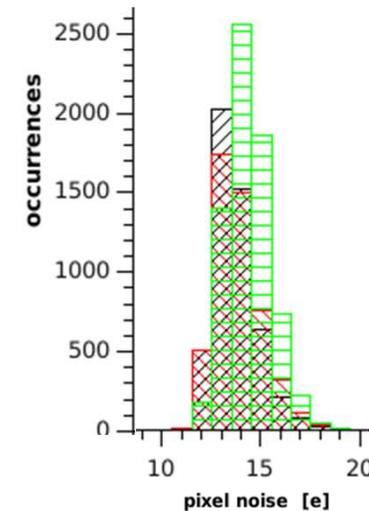


Prototype Performance



- Noise on average below 15e- rms for prototype sensors from different wafers & locations
- Multiple samples of signal & reset levels promise further reduction (prelim tests indicate ~10e- rms achievable)
- Automatic gain adjustment works
- 3 gains accessible via overflow switch architecture
- Dynamic range to 3.5 Me- i.e. 50k photons at 250eV

dispersion of pixel noise values (TS1.2)



Prototype Performance

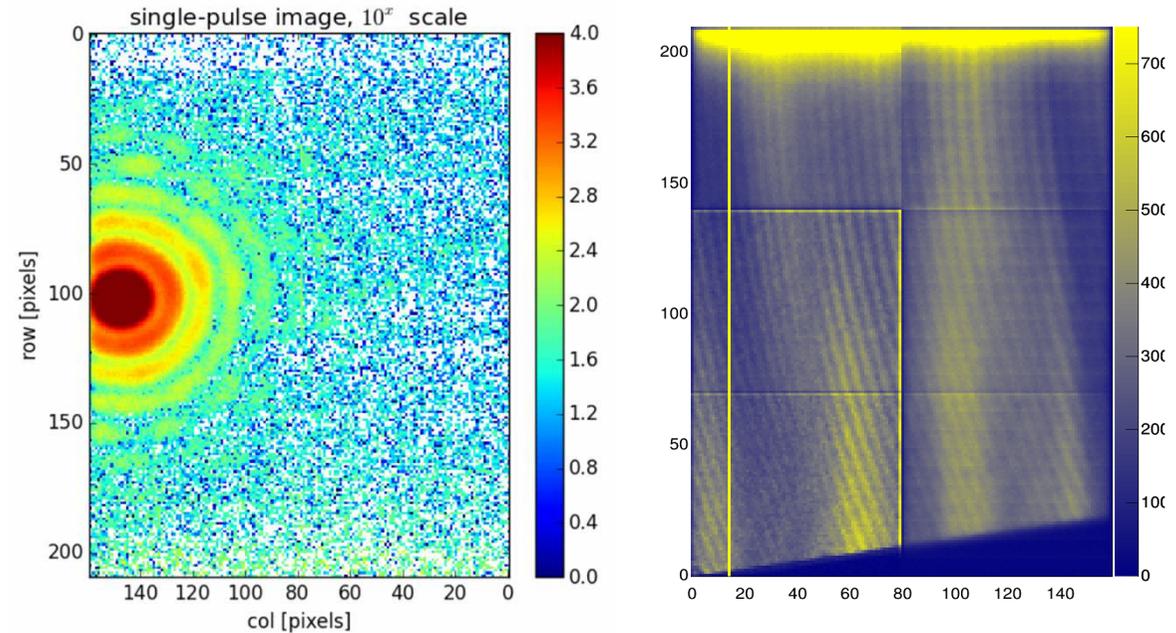


backside-illuminated (BSI)

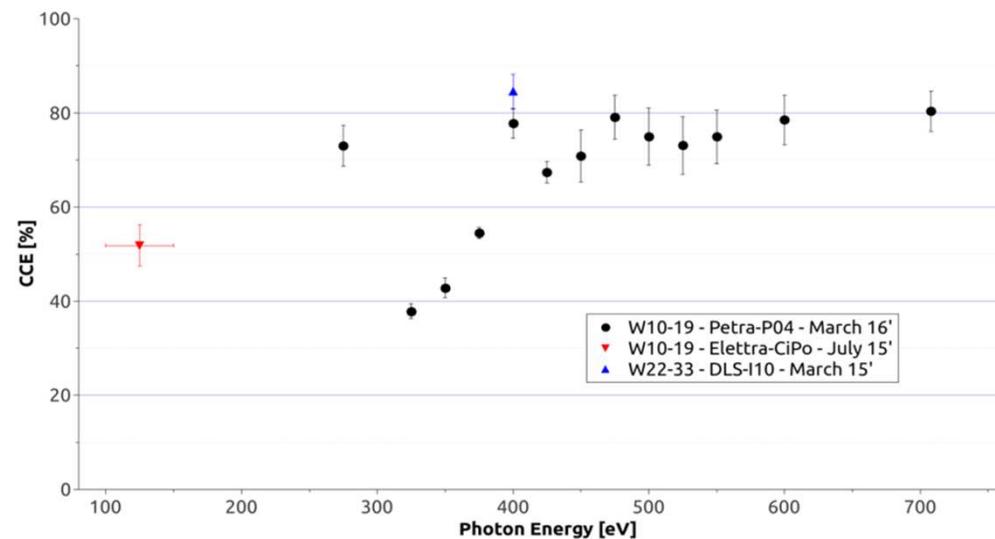
- Imaging at 92 eV, single-shot at FLASH

left: Airy ring pattern

right: fine diffraction rings from liquid sample



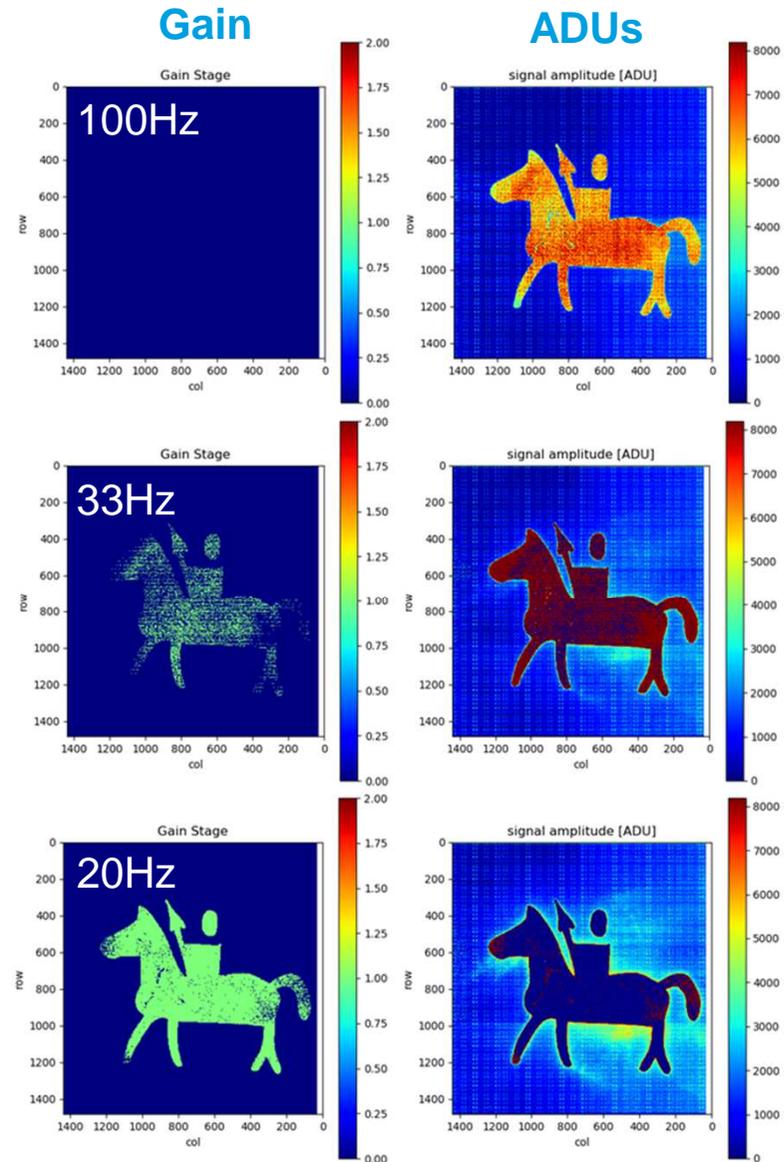
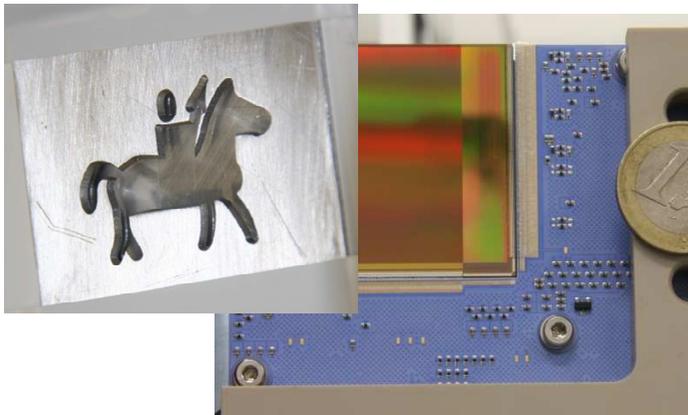
- Airy rings match expectation
- Charge Collection Efficiency (lower limit to Quantum Efficiency) measured at ~70% above 400 eV



P2M Operation



- First light
- Visible light, room temperature
- 100Hz frame rate
(streamout speed of full acquisition system still ramping up)
- Automatic gain switching works

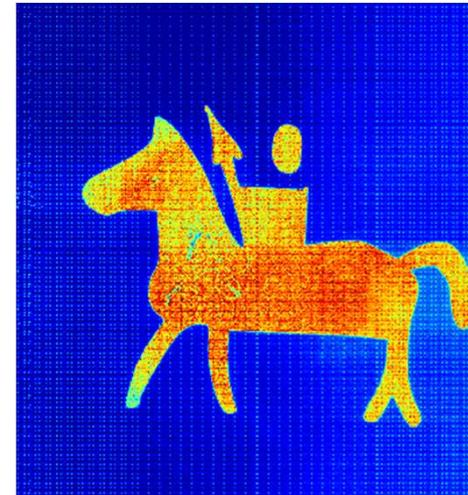


Percival Project Status & Outlook



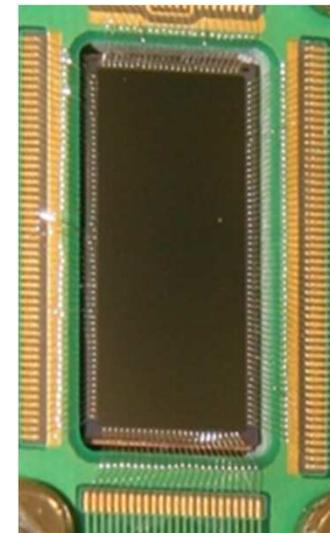
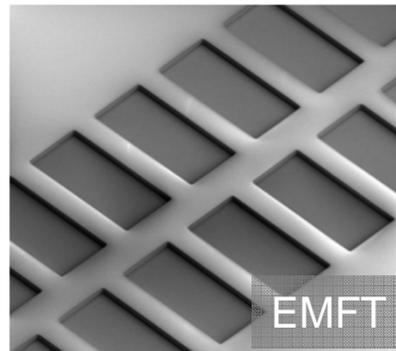
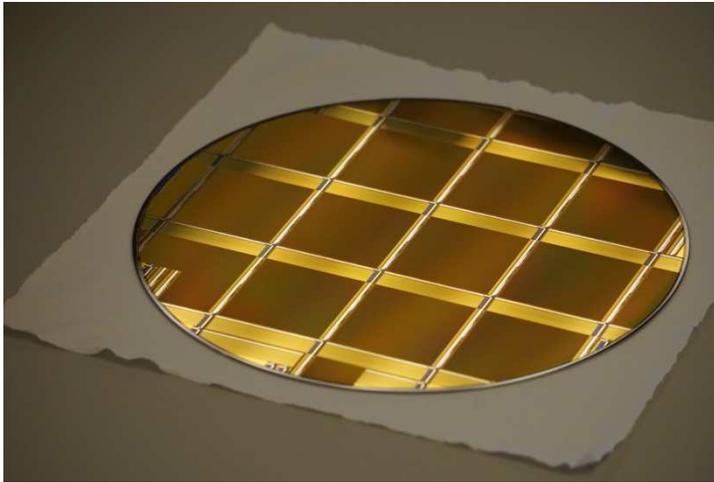
P2M FSI undergoing benchtop testing

- P2M system operates, saw first light
- P2M sensor demonstrates auto gain switching in response to illumination
- Detailed characterization (including bias tweaking etc) ongoing
- Chip functionality at 300Hz frame rate demonstrated, full readout & system ramping up to this
- P2M backthinned sensor in hand, awaiting wirebonding
- Expect first X-ray tests in fall 2018
- First delta-doped P2M BSI ~ Xmas 2018



Post-Processing

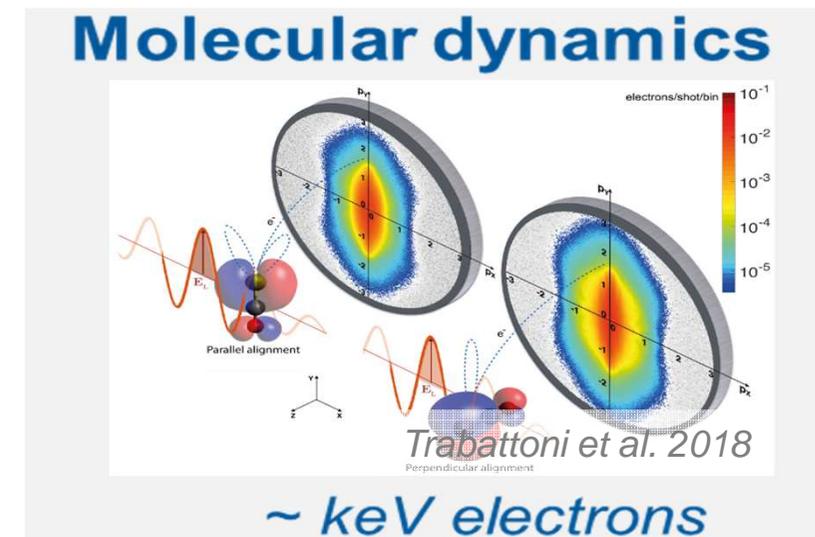
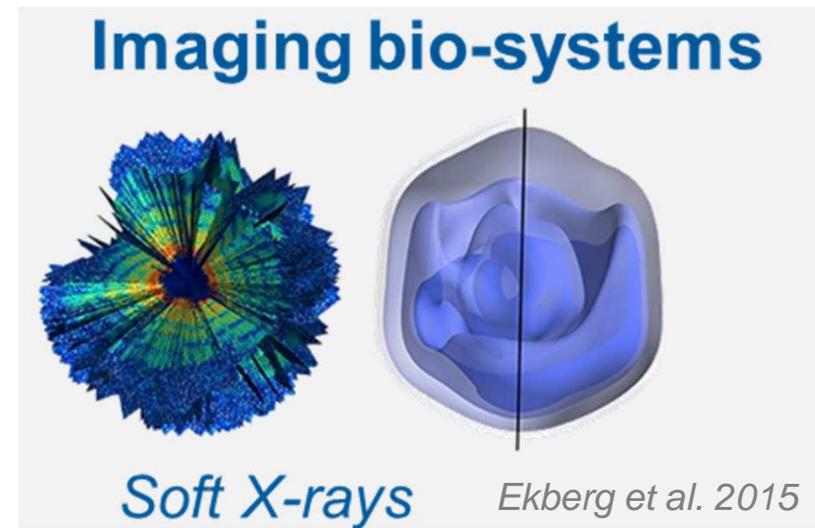
Making Sensors and CMOS Imagers optimally suited for Science



Post-Processing is necessary

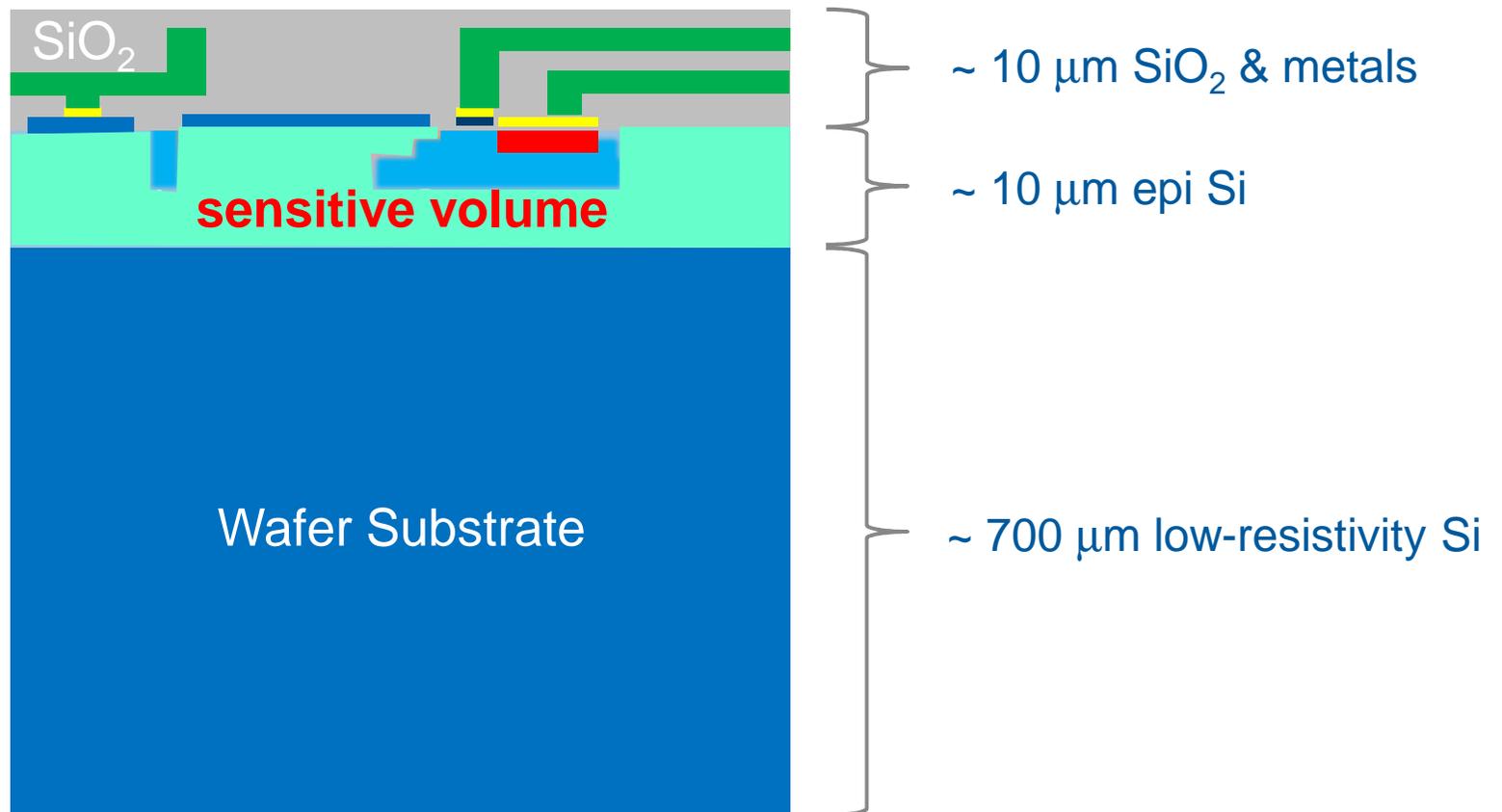
Science challenges – two examples

- Water window offers unique view of biological systems:
Between Carbon and Oxygen edges, water is transparent but carbon absorbs
- 282 eV to 533 eV photons
- Laser-Induced Electron Diffraction:
re-scattered electrons can give simultaneous access to sub-100pm-spatial and sub-fs temporal resolution
- Sweet spot for these measurements is around 500 eV electron energy (plus few keV acceleration from optics)

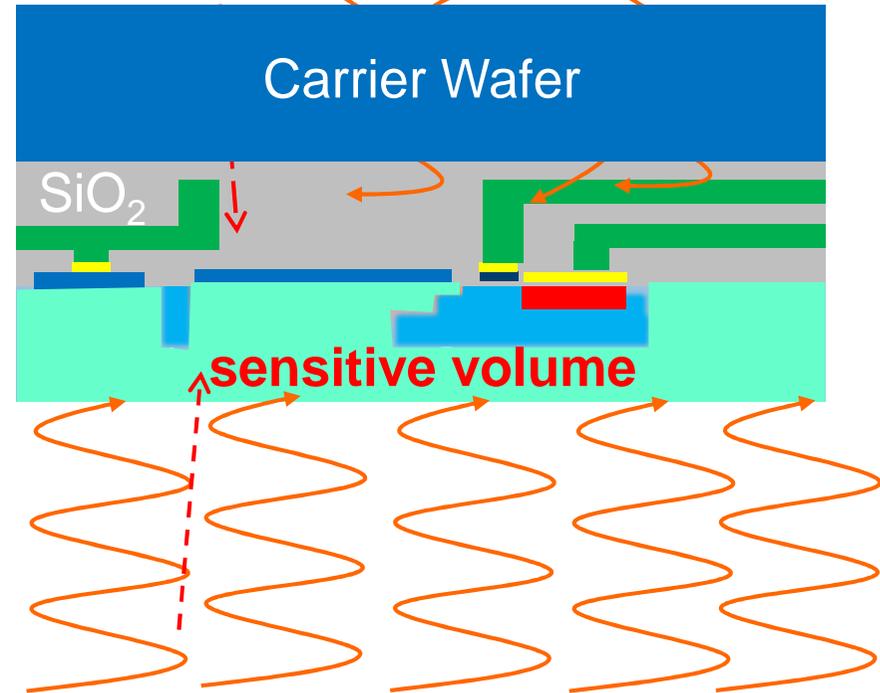
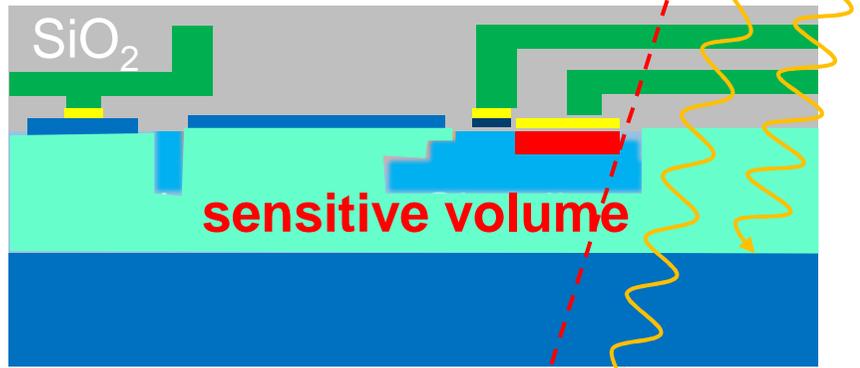


Thinning & backside illumination

CMOS imager one prominent example



Thinning & backside illumination

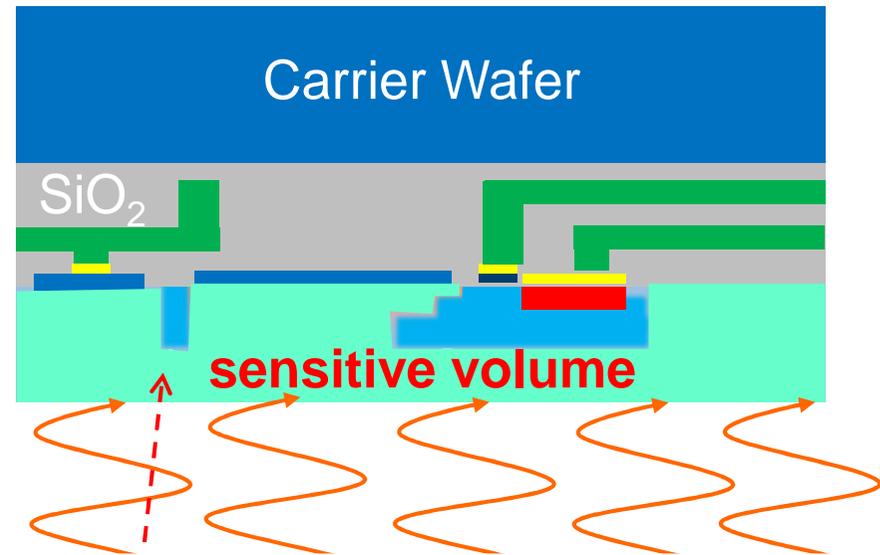


Entrance window post-processing

High sensitivity to low-energy radiation requires:

- Absence of passive material
- Absence of traps
- Optimized field geometry at sensor surface

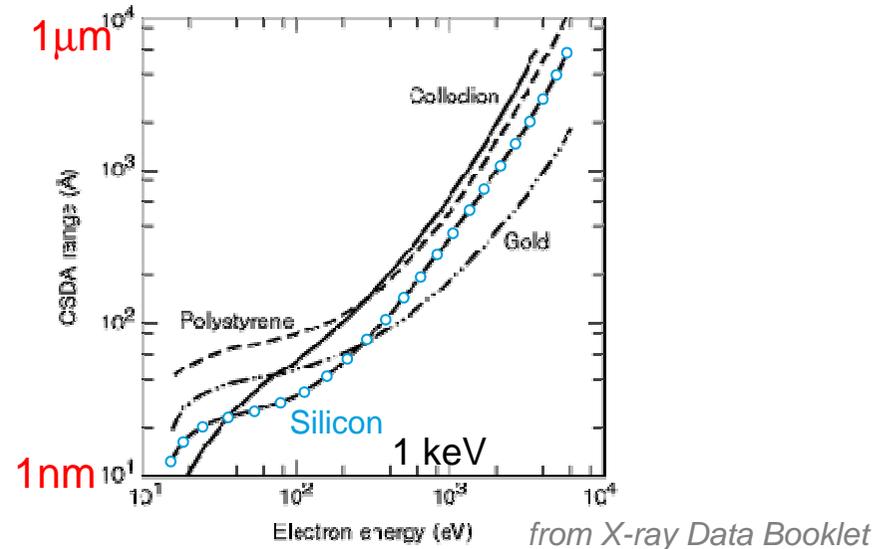
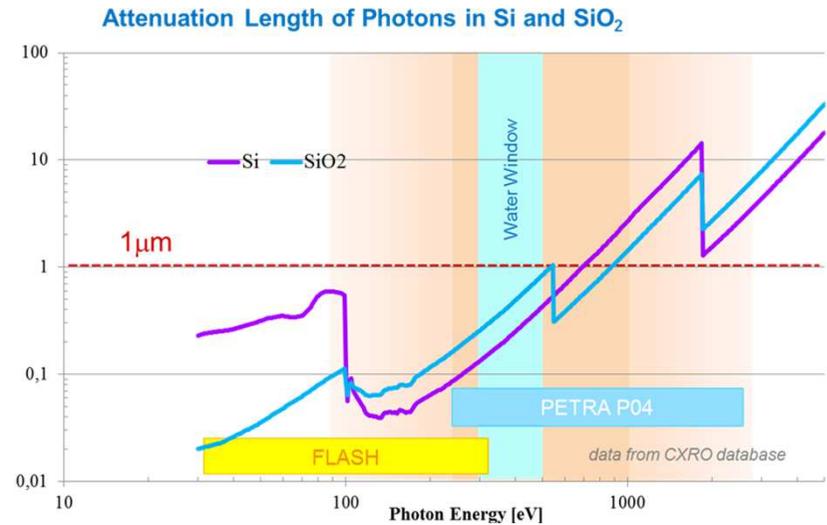
➔ **High-quality backside processing is crucial!**



... and all processes must be high-purity and low-temperature in order to not damage the sensor / circuitry

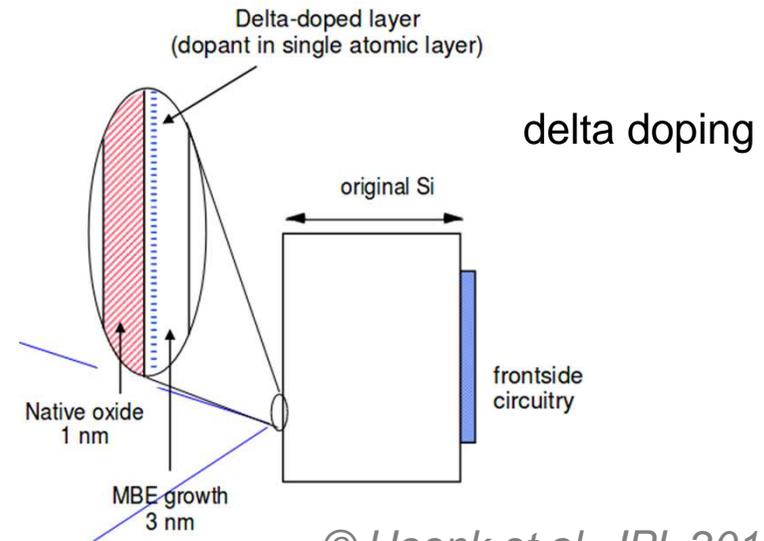
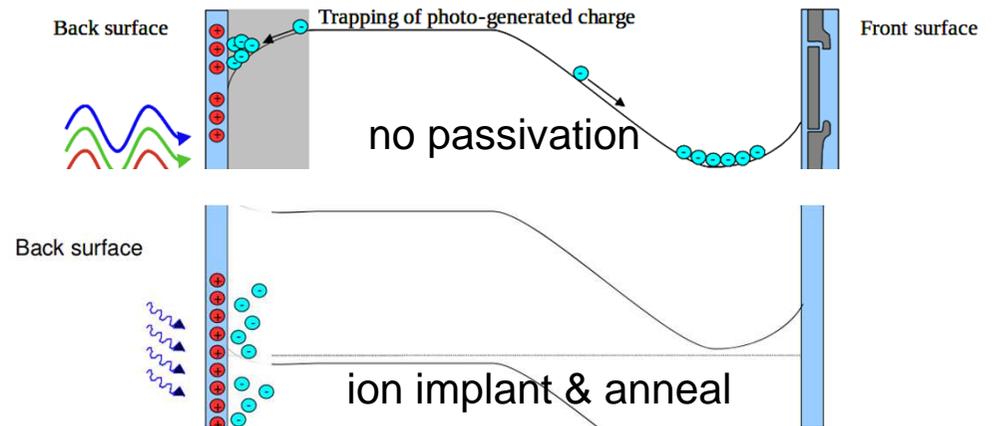
Post-Processing needs

- Attenuation lengths in Si / SiO₂ at or below 100nm for soft X-rays
- Attenuation lengths for few-keV electrons in Si are on the order of 10s of nm
- Interaction must happen in active Si, and generated charge cloud must reach the circuitry
- Requires:
 - Negligible passive layer
 - Negligible traps
 - Optimized geometry of electric field at surface of sensor



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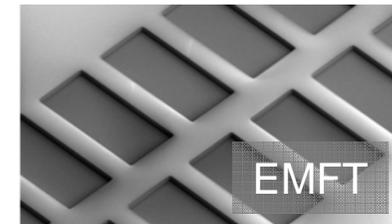
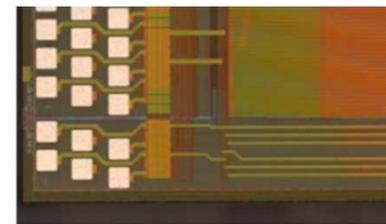
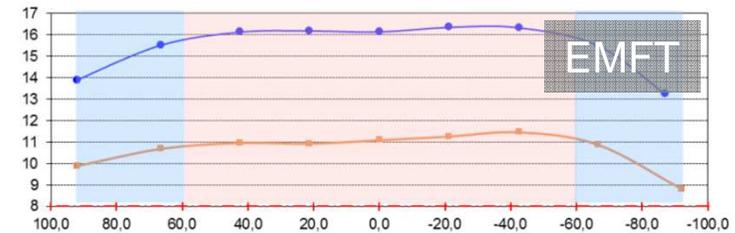


© Hoenk et al, JPL 2010

Post-Processing is a challenge

Optimizing the Sensor for the Science

- Expertise on a range of processing steps necessary
 - Bonding to carrier
 - Thinning with um precision
 - Low-temperature passivation (MBE or e.g. implant & anneal)
 - Pad exposure
 - Material growth such as scintillators
- Molecular Beam Epitaxy (MBE) provides thinnest-known dopant layers
 - “delta doping” pioneered by JPL
- Other US national labs have successfully copied the technique



Post-Processing is a challenge

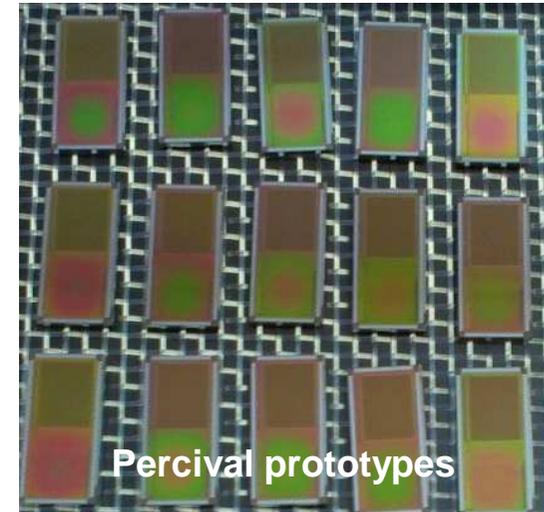
Optimizing the Sensor for the Science

Post-processing of individual chips – as well as full wafers – is crucial:

- Testing successive prototypes under realistic application conditions
- Fast turn-around for effective and rapid sensor optimization

Vision: Custom sensors post-processed to match specific science experiments

- Sensor thickness
- Delta-doping
- Direct-deposited filters with optimized thickness & material
- Adding & modifying structures



Post-Processing for Percival



- Prototype Sensor post-processed by NASA's JPL "delta-doping"
 - Pioneered the approach to ultra-thin entrance windows (few nm)
 - Bureaucratic difficulties mainly make access difficult & time-consuming
 - TS sensors processed by JPL give nice soft X-ray performance
 - Unfortunately e.g. not possible to BSI-process 2nd generation test devices in reasonable time

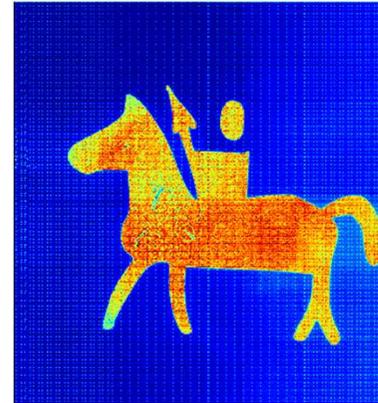


- P2M sensor post-processing
 - JPL remains a key partner and will process wafers
 - Exploring alternate routes to "good" post-processing (for some applications 10s of nm are acceptable)
 - EMFT currently a partner in tests (bonding, thinning, pad exposure)
 - Some routes to thicker dopant layers (10s to 100s of nm) exist, not tried yet
 - Easier-to-access (European / German / Helmholtz) MBE-based post-processing capable of processing both wafers and single (prototype) sensors direly needed



Summary and Outlook

- **Percival P2M System running in the laboratory**
- “kinks” to work out in the details
- Currently tests with FSI sensors and visible light ongoing
- First BSI sensor (thicker entrance window) in hand, tests to commence in July 2018
- **Expect first soft X-ray test in Fall 2018**
- Cloverleaf of 4x 2 Mpixel sensors running at 300Hz
- Can be scaled to 13Mpixel sensor => cloverleaf 52Mpixels at 120Hz
- Data rate (single 2PM 20 Gbit/s) a recognized challenge
IT experts part of team from early stage



- **Postprocessing is a required step for high-performance soft X-ray and low-energy particle detection**
- Industries' interest lower than that of scientists
- Techniques available at few overseas national laboratories, hard to access (politics & time ...)
- **Establishing the required infrastructure and know-how within Helmholtz would form one cornerstone of the coming Distributed Detector Laboratory**

Thank you for your attention!

and

Thanks to Percival collaborators:

DESY:

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